

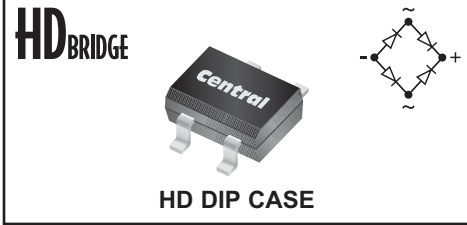
CBRHDSH1-60
SURFACE MOUNT
HIGH DENSITY
1 AMP SILICON
SCHOTTKY BRIDGE RECTIFIER



www.centrasemi.com

DESCRIPTION:

The CENTRAL SEMICONDUCTOR CBRHDSH1-60 is a full wave bridge rectifier mounted in a durable epoxy surface mount molded case, utilizing glass passivated chips.



MARKING CODE: CSH106

FEATURES:

- Low Leakage Current (7.0μA TYP @ V_{RRM})
- High 1.0A Current Rating
- Low V_F Schottky Diodes (600mV MAX @ $I_F=1.0A$)

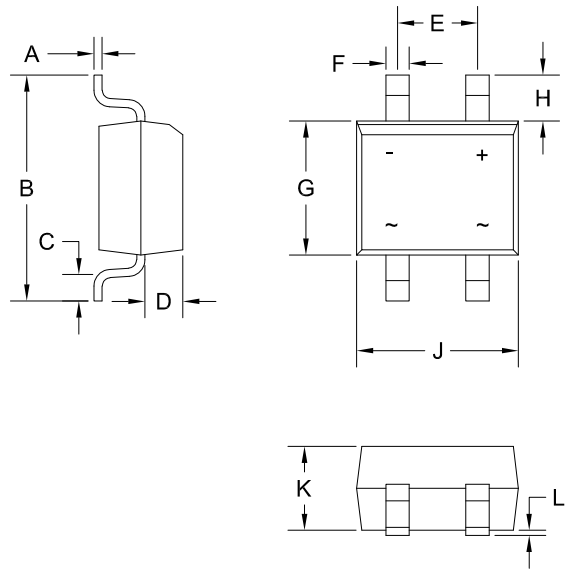
MAXIMUM RATINGS: ($T_A=25^\circ\text{C}$ unless otherwise noted)	SYMBOL		UNITS
Peak Repetitive Reverse Voltage	V_{RRM}	60	V
DC Blocking Voltage	V_R	60	V
RMS Reverse Voltage	$V_{R(RMS)}$	42	V
Average Forward Current	I_O	1.0	A
Peak Forward Surge Current	I_{FSM}	20	A
Power Dissipation	P_D	1.2	W
Operating Junction Temperature	T_J	-50 to +125	$^\circ\text{C}$
Storage Temperature	T_{stg}	-50 to +150	$^\circ\text{C}$
Thermal Resistance	Θ_{JA}	85	$^\circ\text{C}/\text{W}$

ELECTRICAL CHARACTERISTICS PER DIODE: ($T_A=25^\circ\text{C}$ unless otherwise noted)				
SYMBOL	TEST CONDITIONS	TYP	MAX	UNITS
I_R	$V_R=60\text{V}$	7.0	20	μA
I_R	$V_R=60\text{V}, T_A=100^\circ\text{C}$	2.0	10	mA
V_F	$I_F=500\text{mA}$	430	500	mV
V_F	$I_F=1.0\text{A}$	500	600	mV
C_J	$V_R=4.0\text{V}, f=1.0\text{MHz}$	130		pF

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HD DIP CASE - MECHANICAL OUTLINE



R3

SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.006	0.014	0.15	0.35
B	-	0.275	-	7.00
C	0.027	0.043	0.70	1.10
D	0.035	0.051	0.90	1.30
E	0.090	0.106	2.30	2.70
F	0.019	0.031	0.50	0.80
G	0.146	0.165	3.70	4.20
H	0.051	0.067	1.30	1.70
J	0.177	0.193	4.50	4.90
K	0.090	0.106	2.30	2.70
L	0.000	0.008	0.00	0.20

HD DIP (REV: R3)

MARKING CODE: CSH106

R3 (19-August 2020)

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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